

Thermally conductive EMI absorbers are a hybrid of classic gap pad material as well as components that have absorbent properties.

They have a thermal conductivity of 4,0 W/m*K and are available in material thicknesses from 0,5 to 12 mm. The TCMWA series can be supplied as standard sheets or customized stampings, making them suitable for a wide range of applications.

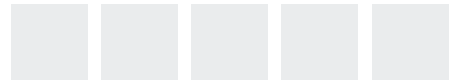
- Thermal conductivity: 4,0 W/m*K
- Excellent absorption characteristics
- Naturally tacky
- Reworkable
- Sheet form
- Die-cut parts



RoHS



REACH

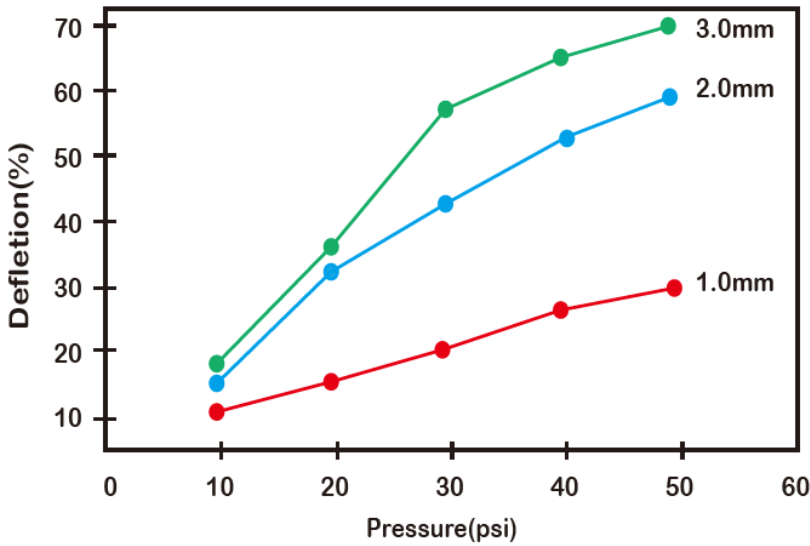


PRODUCT SPECIFICATIONS

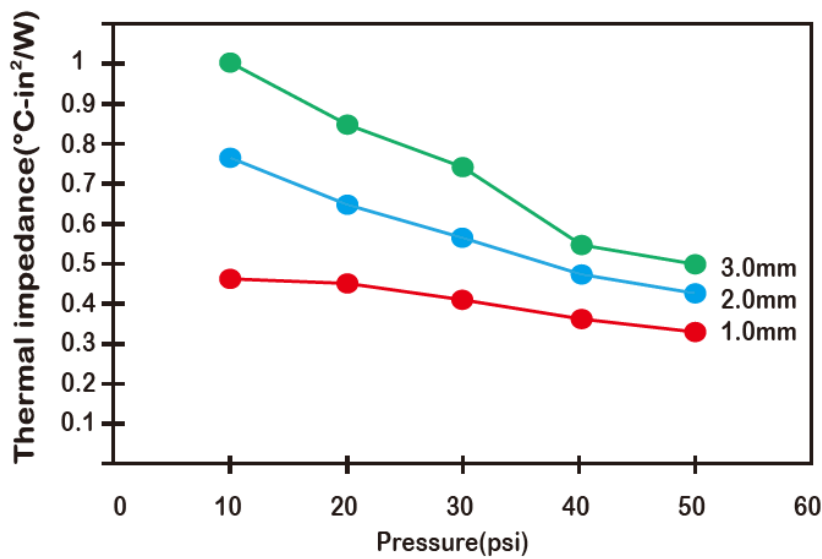
PROPERTY	VALUE / TOLERANCE	TEST METHOD
Basic material	Silicone	-
Thermal conductivity	4,0 W/m*K	ASTM D5470
Hardness	55 Shore 00	ASTM D2240
Density	3,6 g/cm ³	ASTM 792
Temperature range	-60 to 180 °C	internal
Colour	Dark Gray	Visual
EMI Attenuation @5 GHz	11 dB/cm	internal
EMI Attenuation @7 GHz	17 dB/cm	internal
Volume resistivity	> 10 ¹² Ω*m	ASTM D257
Thermal impedance@10psi	0,46 °C-in ² /W	ASTM D5470
Thermal impedance@30psi	0,40 °C-in ² /W	ASTM D5470
Thermal impedance@50psi	0,35 °C-in ² /W	ASTM D5470
Thickness range	0,5 – 12 mm	-
Total mass loss (TML)	0,04%@24h / 150°C	-

Please note: Picture only shows an example of an absorber pad.

DEFLECTION VS PRESSURE

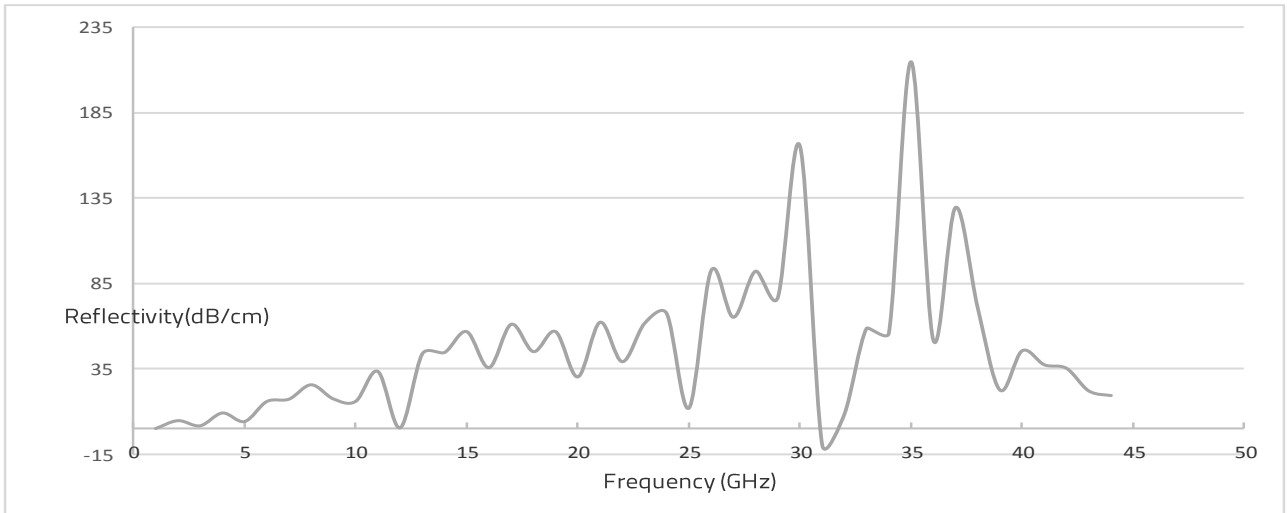


THERMAL IMPEDANCE VS PRESSURE



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REFLECTIVITY PERFORMANCE



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